



Click [here](#) for the 3D model.

### Dimensions

Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
T	0.5mm +/-0.05mm
S	0.3mm MIN
B	0.3mm +/-0.1mm

### Packaging Specifications

Packaging	Waffle, Tray
Packaging Quantity	368

### General Information

Series	SMD Indust COG HT200C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable, Low Loss
Features	High Temp, Ultra-Stable, Low Loss
RoHS	Yes
Termination	Gold
Marking	No
AEC-Q200	No
Component Weight	1.06 mg
Miscellaneous	Moisture Sensitive Packaging. Gold (Au) 100 micro inches min..
Shelf Life	78 Weeks
MSL	1

### Specifications

Capacitance	1000 pF
Measurement Condition	1MHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms